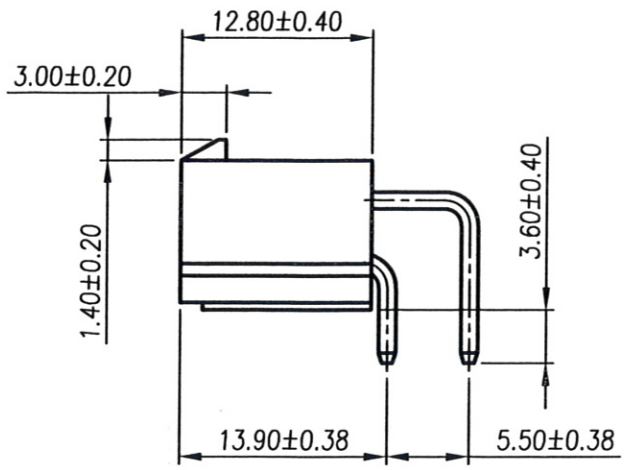


02~12P DIM.A±0.20 ; DIM.B±0.30
 14~24P DIM.A±0.30 ; DIM.B±0.40

PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02		5.6	14	25.2	30.8
04	4.2	9.8	16	29.4	35.0
06	8.4	14.0	18	33.6	39.2
08	12.6	18.2	20	37.8	43.4
10	16.8	22.4	22	42.0	47.6
12	21.0	26.6	24	46.2	51.8



REV	MODIFICATION	DATE	DRAW
A3	ECN20130202	2013.02.26	Seven
A4	ECN20130510	2013.05.23	Michelle
A5	Release To ECN20150406	2015.04.20	Michelle

Specification
 1. Current Rating: See Note 1:
 2. Voltage Rating: 600V AC/DC
 3. Contact Resistance: 20mΩ Max.
 4. Insulation Resistance: 1000MΩ Min.
 5. Dielectric Withstanding Voltage: AC1500V/Minute
 6. Operating Temperature: -40°C~+105°C
 Material:

1. Housing: Thermoplastic UL94V-0 Or UL94V-2
 2. Contact Pin: Copper Alloy SQ Pin 1.14mm
 Finish:
 1. Housing: White
 2. Contact Pin: Bright Tin Plated Over Cu
 Part No.: AD01262 XX X 1 X C
 No. Of Pin: 02~24
 Packing:
 5: Bag
 6: Tray
 Plating:
 1: Bright Tin Plated Over Cu
 Housing Material:
 0: NY66 UL94V-2 White
 1: NY66 UL94V-0 White

Note 1: Current Rating And Wire Size:

Wire Size AWG	Current Rating			
	02	04~06	08~10	12~24
#18	9A	8A	7A	6A
#20	7A	6A	5A	5A
#22	5A	4A	4A	4A
#24	4A	3A	3A	3A

發行
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 文管中心

RoHS Compliant

金上達科技股份有限公司
GOLDENSUNDA TECHNOLOGY CO., LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED
 .X± 0.35 X'± 2"
 .XX± 0.25 X'± 1"
 .XXX± 0.15 X'X'± 0.5"

PROJ. TITLE: Wire To Board Wafer 4.20mm 90° DIP Dual Row
 APR. C.F.Liao 20150420 PART NO. AD01262XXX1XC DWG NO. AD01262XXXX1XC
 CHK. Abel 20150420 UNITS: mm CUSTOMER DRAWING
 DRA. Michelle 20150420 SIZE: A4 SCALE 2:1 SHEET 1 / 1 REV A5 V